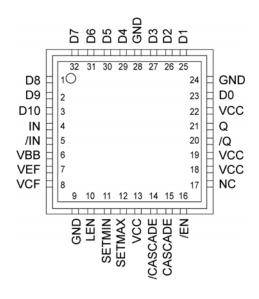
Ordering Information⁽¹⁾

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY89295UMI	MLF-32	Industrial	SY89295U	Sn-Pb
SY89295UMI TR ⁽²⁾	MLF-32	Industrial	SY89295U	Sn-Pb
SY89295UTI	T32-1	Industrial	SY89295U	Sn-Pb
SY89295UTITR ⁽²⁾	T32-1	Industrial	SY89295U	Sn-Pb
SY89295UMG ⁽³⁾	MLF-32	Industrial	SY89295U with Pb-Free bar-line indicator	Pb-Free NiPd Au
SY89295UMGTR ^(2, 3)	MLF-32	Industrial	SY89295U with Pb-Free bar-line indicator	Pb-Free NiPd Au
SY89295UTG ⁽³⁾	T32-1	Industrial	SY89295U with Pb-Free bar-line indicator	Pb-Free NiPd Au
SY89295UTGTR ^(2, 3)	T32-1	Industrial	SY89295U with Pb-Free bar-line indicator	Pb-Free NiPd Au

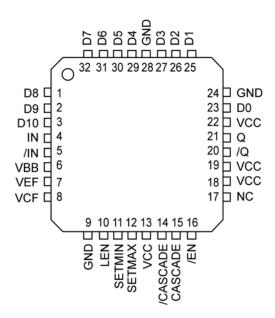
Notes:

- 1. Contact factory for die availability. Dice are guaranteed at T_A = 25°C, DC electricals only.
- Tape and Reel.
- 3. Pb-Free package is recommended for new designs.

Pin Configuration







32-Pin TQFP (T32-1)

Truth Tables

Input/Output

Inputs		Outputs		
IN	IN /IN		/OUT	
0	1	0	1	
1	0	1	0	

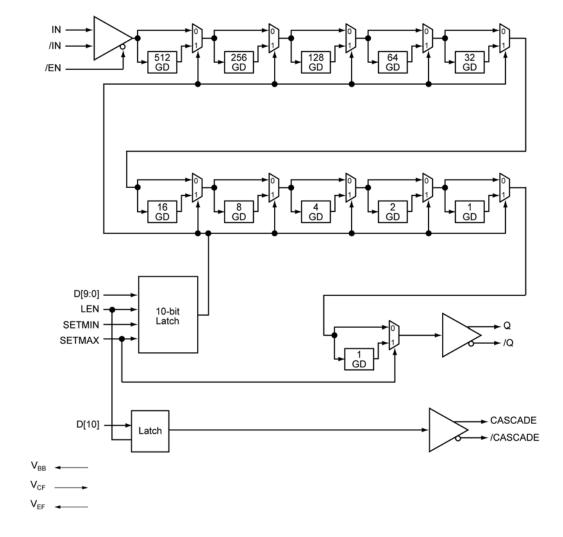
Digital Control Latch

LEN	Latch Action
0	Pass Through D[10:0]
1	Latched

Input Enable

/EN	Q, /Q
0	IN, /IN Delayed
1	Latched D[10:0]

Functional Block Diagram



SY89295U Block Diagram

Pin Description

Pin Number	Pin Name	Pin Function				
23, 25, 26, 27, 29, 30, 31, 32, 1, 2	D[9:0]	"AC Electrical Characteristics" for delay value section which illustrates the proper interfacing D[9:0] contains pull-downs and defaults LOW	CMOS, ECL, or TTL Control Bits: These control signals adjust the delay from IN to Q. See "AC Electrical Characteristics" for delay values. In addition, see "Interface Applications" section which illustrates the proper interfacing techniques for different logic standards. D[9:0] contains pull-downs and defaults LOW when left floating. D0 (LSB), and D9 (MSB). See "Typical Operating Characteristics" for delay information.			
3	D10	CMOS, ECL, or TTL Control Bit: This bit is used to cascade devices for an extended delay range. In addition, it drives CASCADE, and /CASCADE. Further, D[10] contains a bull-down and defaults LOW when left floating.				
4, 5	IN, /IN	LVPECL/ECL Signal Input: Input signal to be will default to a logic LOW if left floating.	delayed. IN contains a 75ký pull-down and			
6	VBB ⁽¹⁾	Reference Voltage Output: When using a sin connect the unused input of the differential pare-bias AC-coupled inputs to IN and /IN. Whe capacitor, otherwise leave floating if not used	air to this pin. This pin can also be used to en used, de-couple to V _{CC} using a 0.01µF			
		Reference Voltage Output: Connect this pin to V _{CF} when D[9:0], and D[10] is ECL				
		Logic Standard V _{CF} Connects to:				
7	VEF	LVPECL V_{EF} ,(1)				
		CMOS No Connect				
		TTL	1.5V Source			
8	VCF	Reference Voltage Input: The voltage driven D[9:0], and D[10].	on V _{CF} sets the logic transition threshold for			
9, 24, 28	GND, Exposed Pad ⁽²⁾	Negative Supply: For MLF® package, expose that is the same potential as the ground pin.	ed pad must be connected to a ground plane			
10	LEN	ECL Control Input: When HIGH latches the Dand D[10] latches are transparent.	0[9:0] and D[10] bits. When LOW, the D[9:0]			
11	SETMIN	ECL Control Input: When HIGH, D[9:0] regist SETMAX or D[9:0] and D[10]. SETMIN conta floating.	ters are reset. When LOW, the delay is set by lins a pull-down and defaults LOW when left			
12	SETMAX	ECL Control Input: When SETMAX is set HIGH and SETMIN is set LOW, D[9:0] = 1111111111. When SETMAX is LOW, the delay is set by SETMIN or D[9:0] and D[10]. SETMAX contains a pull-down and defaults LOW when left floating.				
13, 18, 19, 22	VCC	Positive Power Supply: Bypass with 0.1µF ar	nd 0.01µF low ESR capacitors.			
14, 15	/Cascade, Cascade	LVPECL Differential Output: The outputs are used when cascading two or more SY89295U to extend the delay range.				
16	/EN	LVPECL Single-Ended Control Input: When LOW, Q is delayed from IN. When HIGH, Q is a differential LOW. /EN contains a pull-down and defaults LOW when left floating.				
20, 21	/Q, Q	LVPECL Differential Output: Q is a delayed version of IN. Always terminate the output with 50Ω to $V_{\rm CC}$ – 2V. See "Output Interface Applications" section.				
17	NC	No Connect.				

- 1. Single-ended operation is only functional at 3.3V.
- 2. MLF® package only.

Absolute Maximum Ratings(1)

Supply Voltage (V _{CC})	0.5V to +4.0V
Input Voltage (V _{IN})	–0.5V to V _{CC}
LVPECL Output Current (I _{OUT})	
Continuous	50mA
Surge	100mA
Lead Temperature (soldering, 20 sec.)	+260°C
Storage Temperature Range (T _S)	65°C to +150°C

Operating Ratings⁽²⁾

Supply Voltage (V _{CC}) Ambient Temperature (T _A)	
Package Thermal Resistance ⁽³⁾ $MLF^{\otimes}(\theta_{JA})$	
Still-Air ·····	35°C/W
$MLF^{ ext{@}}\left(\psi_{JB}\right)$	
Junction-to-Board ······	28°C/W
TQFP (θ_{JA})	
Still-Air ·····	28°C/W
TQFP (ψ_{JB})	
Junction-to-Board ·····	20°C/W

DC Electrical Characteristics⁽⁴⁾

 $T_A = -40$ °C to +85°C, unless noted.

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
V _{CC}	Power Supply	V _{CC} = 2.5V	2.375	2.5	2.625	V
		V _{CC} = 3.3V	3	3.3	3.6	
I _{EE}	Power Supply Current	No load, max. V _{CC}			220	mA
V _{IN}	Input Voltage Swing (IN, /IN)	See Figure 1a.	150		1200	mV
V _{DIFF_IN}	Differential Input Voltage Swing (IN, /IN)	See Figure 1b.	300		2400	mV
V _{IHCMR}	Input High Common Mode Range	IN, /IN	V _{EE} + 1.2		V _{CC}	V

 V_{CC} = 3.3V, T_A = -40°C to 85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
V _{IH}	Input High Voltage (IN, /IN)		2.075		2.420	V
V _{IL}	Input Low High Voltage (IN, /IN)		1.355		1.675	V
V_{BB}	Output Voltage Reference		1.775	1.875	1.975	V
V _{EF}	Mode Connection		1.9	2.0	2.1	V
V _{CF}	Input Select Voltage		1.55	1.65	1.75	V

Notes:

- 1. Permanent device damage may occur if "Absolute Maximum Ratings" are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to "Absolute Maximum Rating" conditions for extended periods may affect device reliability.
- 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- 3. Thermal performance on MLF® packages assumes exposed pad is soldered (or equivalent) to the device most negative potential (GND).
- 4. The circuit is designed to meet the DC specifications shown in the table above after thermal equilibrium has been established. Input and output parameters vary 1:1 with V_{CC}, with the exception of V_{CF}.

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DC Electrical Characteristics⁽⁴⁾ (Continued)

 V_{CC} = 2.5V, T_A = -40°C to 85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
V _{IH}	Input High Voltage (IN, /IN)		1.275		1.62	V
V _{IL}	Input Low High Voltage (IN, /IN)		0.555		0.875	V
V _{BB}	Output Voltage Reference		1.175	1.075	0.975	V
V _{EF}	Mode Connection		1.10	1.20	1.30	V
V _{CF}	Input Select Voltage		1.15	1.25	1.35	V

LVPECL Outputs DC Electrical Characteristics⁽⁴⁾

 V_{CC} = 3.3V; R_{LOAD} = 50 Ω to V_{CC} -2V; T_A = -40°C to +85°C, unless noted.

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
V _{OH}	Output HIGH Voltage (Q, /Q)		2.155	2.280	2.405	V
V _{OL}	Output LOW Voltage (Q, /Q)		1.355	1.480	1.605	V
V _{OUT}	Output Voltage Swing (Q, /Q)	See Figure 1a.	550	800		mV
V _{DIFF_OUT}	Differential Output Voltage Swing (Q, /Q)	See Figure 1b.	1.1	1.6		V

LVPECL Outputs DC Electrical Characteristics⁽⁵⁾

 V_{CC} = 2.5V; R_{LOAD} = 50 Ω to V_{CC} -2V; T_A = -40°C to +85°C, unless noted.

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
V _{CC}	Output HIGH Voltage (Q, /Q)		1.355	1.480	1.605	٧
I _{EE}	Output LOW Voltage (Q, /Q)		0.555	0.68	0.805	V
V _{IN}	Output Voltage Swing (Q, /Q)	See Figure 1a.	550	800		mV
V _{DIFF_OUT}	Differential Output Voltage Swing (Q, /Q)	See Figure 1b.	1.1	1.6		V

LVTTL/CMOS DC Electrical Characteristics⁽⁶⁾

 V_{CC} = 2.5V ±5% or 3.3V ±10%; T_A = -40°C to +85°C, unless noted.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{IH}	Input HIGH Voltage		2.0			\
V _{IL}	Input LOW Voltage				0.8	V
I _{IH}	Input HIGH Current				40	μΑ
I _{IL}	Input LOW Current		-300			μΑ

- The circuit is designed to meet the DC specifications shown in the table above after thermal equilibrium has been established. V_{OH} and V_{OL} parameters vary 1:1 with V_{CC}.
- 6. The circuit is designed to meet the DC specifications shown in the table above after thermal equilibrium has been established.

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AC Electrical Characteristics⁽⁷⁾

 $T_A = -40$ °C to +85°C, unless noted.

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
f_{MAX}	Maximum Operating Frequency	Clock V _{OUT} ≥ 400mV	1.5			GHz
t _{pd}	Propagation Delay IN to Q; D[0–10]=0 IN to Q; D[0–10]=1023 /EN to Q: D[0–10]=0 D10 to CASCADE		3200 11500 3400 350		4200 14800 4400 670	ps
t _{RANGE}	Programmable Range $t_{pd} (\text{max.}) - t_{pd} (\text{min})$		8300			ps
t _{SKEW}	Duty Cycle Skew t _{PHL} - t _{PLH}	Note 8			25	ps
Δt	Step Delay D0 High D1 High D2 High D3 High D4 High D5 High D6 High D7 High D8 High D9 High			10 15 35 70 145 290 575 1150 2300 4610 9220		ps
INL	Integral Non-Linearity	Note 9		±10		ps
t _S	Setup Time D to LEN D to IN /EN to IN	Note 10 Note 11	200 350 300			ps
t _H	Hold Time LEN to D IN to /EN	Note 12	200 400			ps

- 7. High-frequency AC electricals are guaranteed by design and characterization.
- Duty cycle skew guaranteed only for differential operation measured from the cross point of the input to the crosspoint of the output.
- INL (Integral Non-Linearity) is defined from its corresponding point on the ideal delay versus D[9:0] curve as the deviation from its ideal delay. The maximum difference is the INL. Theoretical Ideal Linearity (TIL) = (measured maximum delay - measured minimum delay) ÷ 1024. INL = measured delay – measured minimum delay + (step number ∞ TIL).
- 10. This setup time defines the amount of time prior to the input signal. The delay tap of the device must be set.
- 11. This setup time defines the amount of the time that /EN must be asserted prior to the next transition of IN, /IN to prevent an output response greater than ±75mV to the IN, /IN transition.
- 12. Hold time is the minimum time that /EN must remain asserted after a negative going IN or a positive going /IN to prevent an output response greater than ±75mV to the IN, /IN transition.

AC Electrical Characteristics⁽⁷⁾

 $T_A = -40$ °C to +85°C, unless noted.

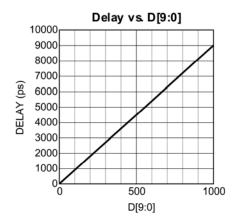
Symbol	Parameter	Condition	Min.	Тур.	Max.	Units	
	Release Time						
t_R	/EN to IN		500			ps	
	SETMAX to LEN SETMIN to LEN		500 450				
	SETWIN to LEN		450				
t _{JITTER}	Cycle-to-Cycle Jitter	Note 13			2	ps _{RMS}	
	Total Jitter	Note 14			10	ps _{PP}	
	Random Jitter	Note 15			1	ps _{RMS}	
t _r , t _f	Output Rise/Fall Time	20% to 80% (Q) 20% to 80% (Cascade)	50 90	85	160 300	ps	
	Duty Cycle		45		55	%	

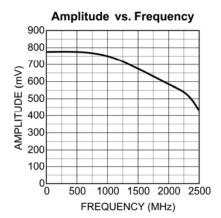
- 13. Cycle-to-cycle jitter definition: The variation of periods between adjacent cycles over a random sample of adjacent cycle pairs. $T_{\text{jitter_cc}} = T_n T_n + 1$, where T is the time between rising edges of the output signal.
- 14. Total jitter definition: With an ideal clock input, no more than one output edge in 10¹² output edges will deviate by more than the specified peak-to-peak jitter value.
- 15. Random jitter definition: Jitter that is characterized by a Gaussian distribution, unbounded and is quantified by its standard deviation and mean. Random jitter is measured with a K28.7 comma defect pattern, measured at 1.5Gbps.

Typical Operating Characteristics

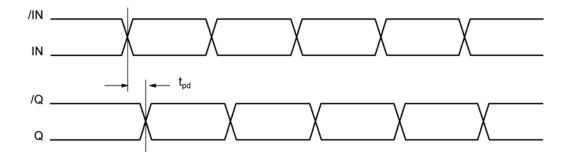
Downloaded from Arrow.com.

 V_{CC} = 3.3V, GND = 0, D_{IN} = 100mV, T_A = 25°C, unless otherwise stated.





Timing Diagrams



Single-Ended and Differential Swings



Figure 1a. Single-Ended Voltage Swing

Figure 1b. Differential Voltage Swing

Input and Output Stages

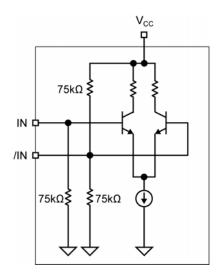


Figure 2a. Differential Input Stage

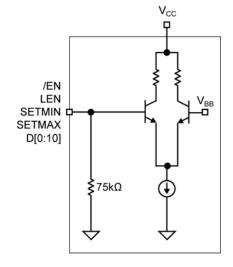


Figure 2b. Single-Ended Input Stage

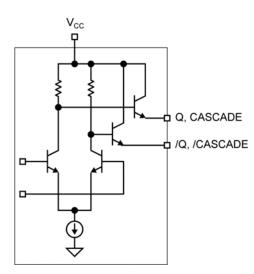


Figure 3. LVPECL Output Stage

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Output Interface Applications

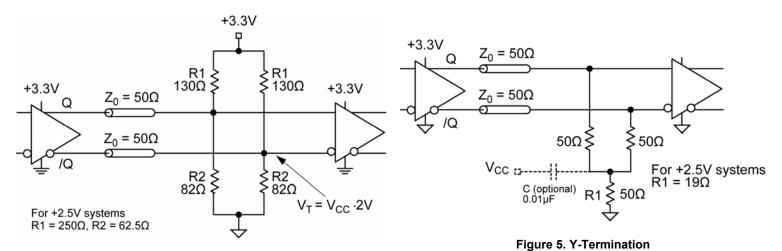
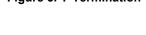
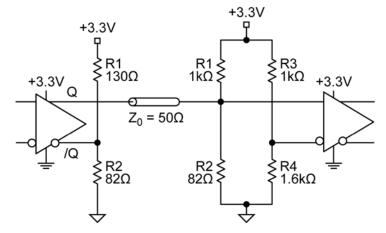


Figure 4. Parallel Termination





For +2.5V systems $R1 = 250\Omega$, $R2 = 62.5\Omega$, $R3 = 1.25k\Omega$, $R4 = 1.2k\Omega$

Figure 6. Terminating Unused I/O

Applications Information

For best performance, use good high-frequency layout techniques, filter V_{CC} supplies, and keep ground connections short. Use multiple vias where possible. Also, use controlled impedance transmission lines to interface with the SY89295U data inputs and outputs.

V_{BB} Reference

The VBB pin is an internally generated reference and is available for use only by the SY89295U. When unused, this pin should be left unconnected. Two common uses for V_{BB} are to handle a single-ended PECL input, and to re-bias inputs for AC-coupling applications.

If IN and /IN are driven by a single-ended output, V_{BB} is used to bias the unused input. Please refer to Figure 10. The PECL signal driving the SY89295U may optionally be inverted in this case.

When the signal is AC-coupled, V_{BB} is used, as shown in Figure 13, to re-bias IN and /IN. This ensures that SY89295U inputs are within acceptable common mode range.

In all cases, V_{BB} current sinking or sourcing must be limited to 0.5mA or less.

Setting D Input Logic Thresholds

In all designs where the SY89295U GND supply is at zero volts, the D inputs can accommodate CMOS and TTL level signals, as well as PECL or LVPECL. Figures 11, 12 and 14 show how to connect V_{CF} and V_{EF} for all possible cases.

Cascading

Two or more SY89295U may be cascaded in order to extend the range of delays permitted. Each additional SY89295U adds about 3.2ns to the minimum delay and adds another 10240ps to the delay range.

Internal cascade circuitry has been included in the SY89295U. Using this internal circuitry, the SY89295U may be cascaded without any external gating.

Examples of cascading 2, 3, or 4 SY89295U appear in Figures 7, 8, and 9.

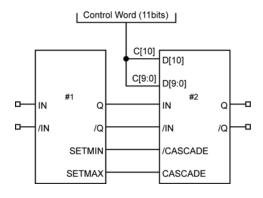


Figure 7. Cascading Two SY89295U

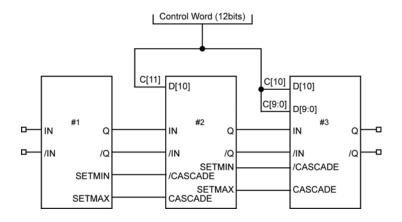


Figure 8. Cascading Three SY89295U

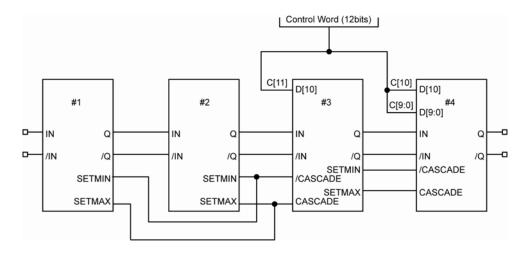
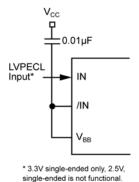
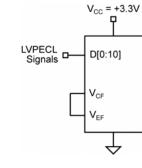


Figure 8. Cascading Four SY89295U

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Interface Applications





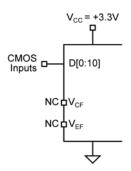
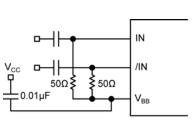
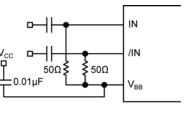


Figure 10. Interfacing to a Single-Ended LVPECL Signal

Figure 11. V_{CF}/V_{EF} Biasing for LVPECL Control (D) Input

Figure 12. $V_{\text{CF}}/V_{\text{EF}}$ Biasing for CMOS (D) Input





 $V_{CC} = +3.3V$ TTL D[0:10] Inputs $1.5k\Omega$ 0.01µF

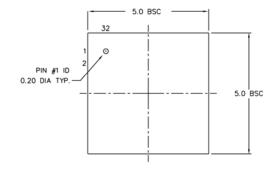
Figure 13. Re-Biasing an **AC-Coupled Signal**

Figure 14. V_{CF}/V_{EF} Biasing for **LVTTL Control (D) Input**

Related Product and Support Documentation

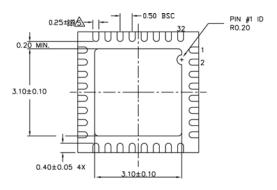
Part Number	Function	Datasheet Link	
SY89295U	2.5/3.3V 1.5GHz Precision LVPECL Programmable Delay	www.micrel.com/product-info/products/sy89295u.shtml	
SY89296U	2.5/3.3V 1.5GHz Precision LVPECL Programmable Delay with Fine Tune Control	www.micrel.com/product-info/products/sy89296u.shtml	
	16-MLF Manufacturing Guidelines Exposed Pad Application Note	www.amkor.com/products/notes papers/MLF appnote 0902.pdf	
	HBW Solutions	http://www.micrel.com/product-info/as/solutions.shtml	

Package Information



TOP VIEW





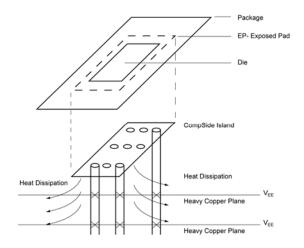
 $\mathsf{T} \square \mathsf{M}$

TE:
ALL DIMENSIONS ARE IN MILLIMETERS.
MAX. PACKAGE WARPAGE IS 0.05 mm.
MAXIMUM ALLOWABE BURRS IS 0.076 mm IN ALL DIRECTIONS.
PIN #1 ID ON TOP WILL BE LASSE/INK MARKED.
DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED
BETWEEN 0.20 AND 0.25 mm FROM TERMINAL TIP.
APPLIED ONLY FOR TERMINALS.

APPLIED FOR EXPOSED PAD AND TERMINALS.

SIDE VIEW

MLF55Q-32LD-PD-2-B



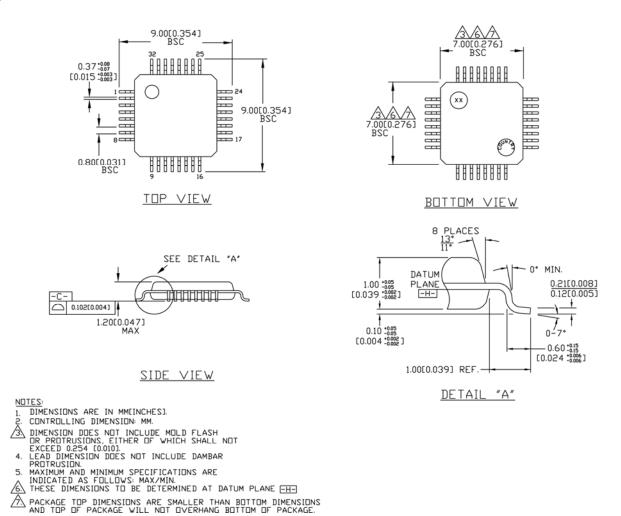
PCB Thermal Consideration for 32-Pin MLF® Package (Always solder, or equivalent, the exposed pad to the PCB)

Package Notes:

- 1. Package meets Level 2 qualifications
- 2. All parts are dry-packed before shipment.
- 3. Exposed pads must be soldered to a ground for proper thermal management.

32-Pin MLF® (MLF-32)

Package Information (Continued)



32-Pin TQFP (T32-1)

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